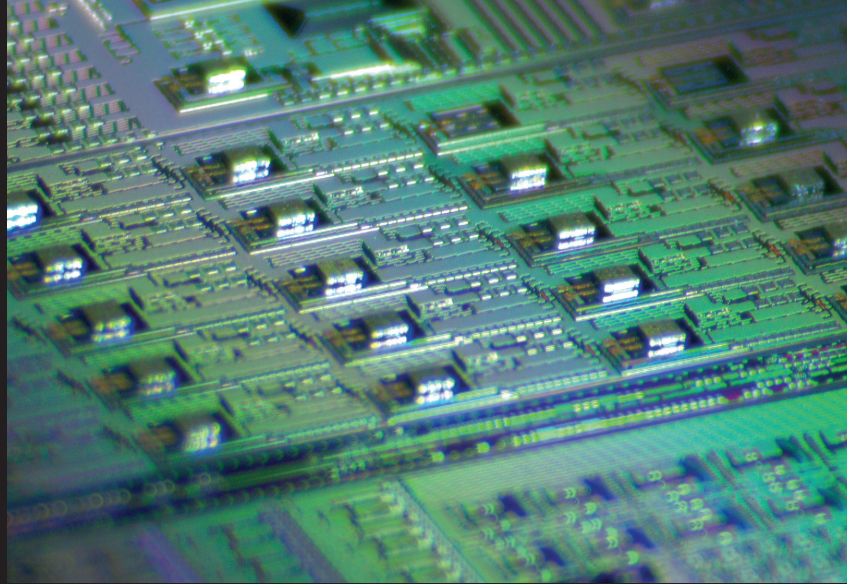
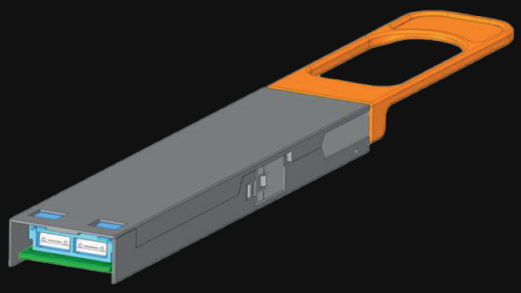
MicroVision®

Multi-spectral ELS* for Scale-Up



Main Features

- **OCI-MSA* compliant**, bare chip engine and OIF-ELSFP* form factor with blind-mate optical interface
- **8 wavelengths on OCI-MSA grid**, groups A and B, 1308.00 to 1334.78 nm
- **> 20 dBm per wavelength in fiber**
- **Power variation channel-to-channel <0.5 dB**
- **Absolute wavelength lock to ±0.1 nm with low thermal wavelength sensitivity**
- **< 100 kHz linewidth**, constant across the full power range
- **14 dB programmed output range**, wavelength-invariant
- **Flip-chip integrated known-good-die**, wafer-scale passive alignment



Optical specifications

Parameter	Min	Typ	Max	Unit
Wavelengths, OCI grid A and B	8			
Wavelength accuracy, absolute, over life and temperature	−0.2	±0.1	+0.2	nm
Output power per wavelength, in fiber		20		dBm
Aggregated output power per fiber		26		dBm
Commandable attenuation range, ΔP_ELS	0		14	dB
Wavelength shift over the full attenuation range			±0.02	nm
Linewidth		50	100	kHz

Parameter	Min	Typ	Max	Unit
RIN, 0.1 to 20 GHz		−157	−150	dB/Hz
Side-mode suppression ratio	45	55		dB
Polarisation extinction ratio	20	23		dB
Output reflectance			-26	dB
Optical return loss tolerance			-26	dB
Optical interface		MT-12, 2 PM fibers, blind-mate, Conventional keying		
Initialisation time		500		ms

*ELS = External Laser Source | OCI-MSA = Optical Compute Interconnect Multi-Source Agreement
OIF= Optical Internetworking Forum | ELSFP = External Laser Small Form-Factor Pluggable

Contact Davide Canavesi: davide_canavesi@microvision.com

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